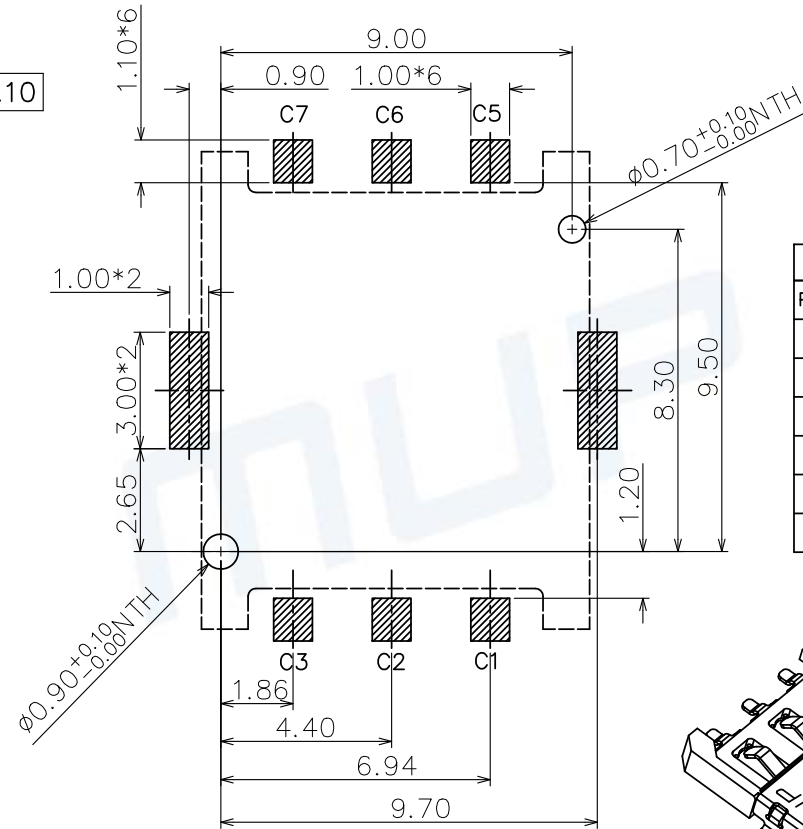
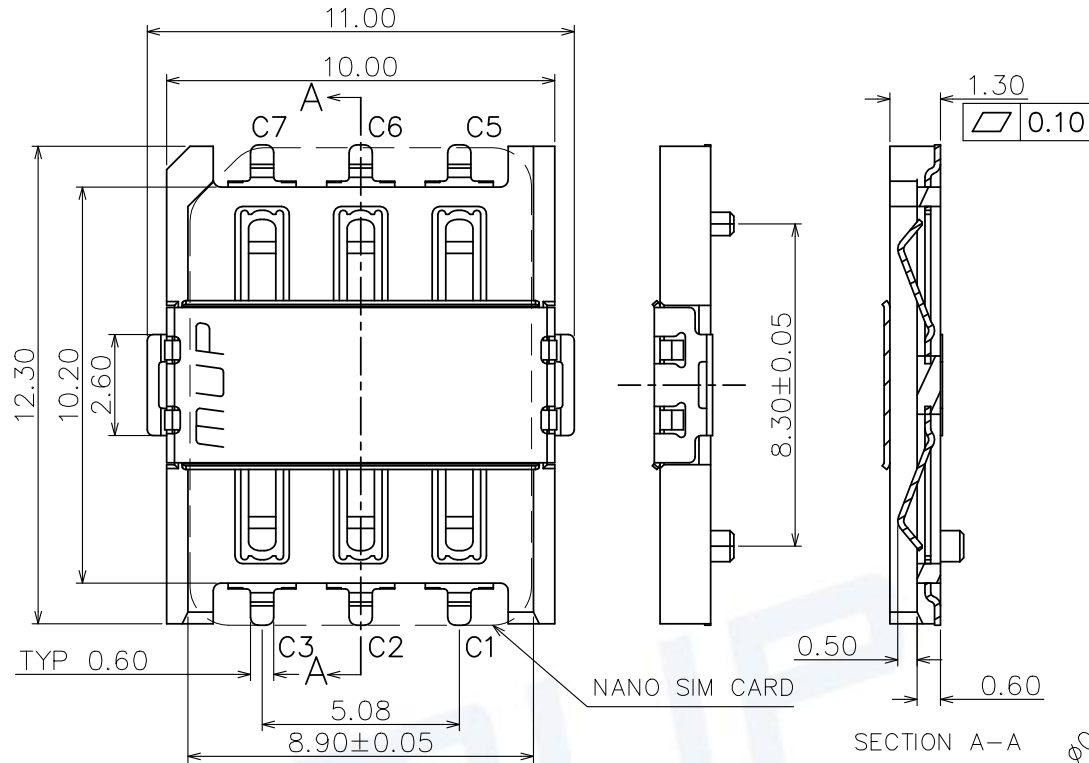
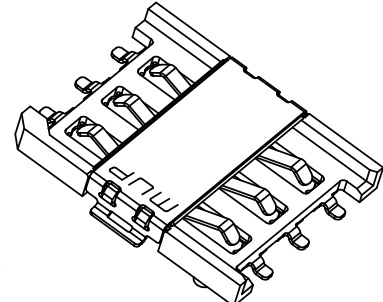


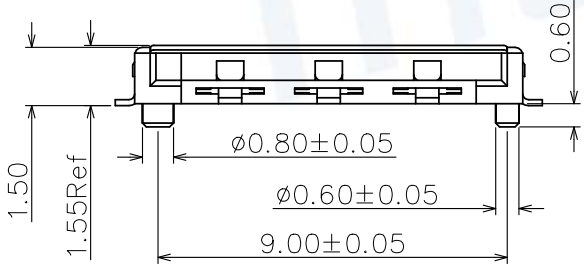
REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1	NEW REVISION				Henry Apr.09.2014
X2					



Nano-SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



RECOMMENDED P.C.B LAYOUT  
COMPONENT SIDE(TOLERANCE ±0.05)



**TECHNICAL CHARACTERISTICS**

1.General Characteristics  
 Dimensions: 12.30LX10.00WX1.50H mm  
 Weight: Approx 0.53±0.2g  
 Durability: 1,500 cycles min.

2.Electrical Characteristics  
 Contact resistance: 50mΩ typical, 100mΩ max  
 Insulation resistance: >1000MΩ/500V DC

3.Solderability  
 Vaporphase: 215°C, 30sec.Max  
 IR reflow: 250°C, 5sec.Max  
 Manual soldering: 370°C, 3sec.Max

4.Environmental Characteristics  
 Operating temperature: -40°C~+85°C  
 Operating humidity: 10%~+95%RH

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	6	Copper Alloy	Contact area:Gold plated
3	SHELL	1	Stainless Steel	SMT area:Gold plated

Unless otherwise specified, other tolerance are:

**MUP** MUP INDUSTRIAL CO.,LTD.

NAME: **Nano-SIM Card Connector**

MODEL NO: **MUP-C781-1**

TYPE: **H1.50mm 6 PIN**

PROJ.	UNIT	SCALE	DRAWN	Henry Apr.09.2014	DWG NO.:
①	mm	1:1	CHECKED	Henry Apr.09.2014	DWG-MUP-C781-1
CUSTOMER DRAWING			APPROVAL	Simon Apr.09.2014	SHEET
					1/1
					REVISION
					X1

